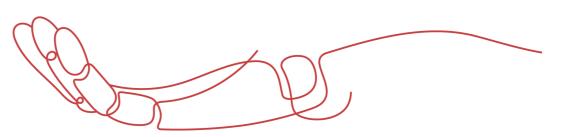




PRODUCT DATA SHEET



To learn more about JGSEMI, please visit our website at







Datasheet

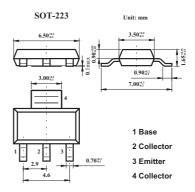
ces Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

NPN Silicon Planar Medium Power Transistor

Features

Low saturation voltage



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit
Collector-Base Voltage	Vсво	300	V
Collector-Emitter Voltage	Vceo	300	V
Emitter-Base Voltage	VEBO	5	V
Peak Pulse Current	Ісм	1	А
Continuous Collector Current	Ic	0.5	А
Power Dissipation at T _{amb} =25℃	Ptot	2	W
Operating and Storage Temperature Range	Tj:Tstg	-55 to +150	${\mathbb C}$

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Тур.	Max	Unit
Collector-Base Breakdown Voltage	V(BR)CBO	Ic=100μA	300			V
Collector-Emitter Breakdown Voltage	V(BR)CEO	Ic=10mA*	300			V
Emitter-Base Breakdown Voltage	V(BR)EBO	IE=100μA	5			V
Collector Cut-Off Current	Ісво	VcB=200V			0.1	μΑ
Emitter Cut-Off Current	ІЕВО	VEB=3V			0.1	μΑ
Collector-Emitter Saturation Voltage	VCE(sat)	Ic=100mA, Iв=10mA*			0.5	V
Base-Emitter Saturation Voltage	VBE(sat)	Ic=100mA, Iв=10mA*			1.0	V
Base-Emitter Turn-On Voltage	VBE(on)	Ic=100mA, VcE=5V*			1.0	V
Static Forward Current Transfer Ratio	hFE	Ic=10mA, VcE =5V*	40			
		Ic=100mA, VcE =5V*	50			
Transition Frequency	fτ	Ic=10mA, VcE =20V,f=20MHz	30			MHz
Output Capacitance	Cobo	Vcb =20V, f=1MHz			20	pF

^{*} Measured under pulsed conditions. Pulse Width=300 μ s. Duty cycle \lesssim 2%



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